

**HeBoFill®** 501 is a pure Boron Nitride powder with a coarse grain size distribution. Its average particle size is 45  $\mu$ m. The extremely low specific surface area allows high filler loadings with a minimum viscosity increase. It is particularly suitable as a filler in polymers, allowing the thermal conductivity to be increased without affecting the electrically insulating properties.

#### **Advantages**

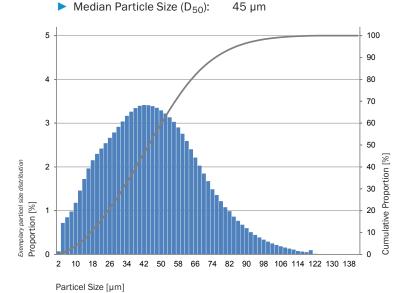
- ▶ Very high thermal conductivity also at low filler loadings
- ► Electrically insulating
- High purity
- Very low specific surface area
- Provides high filler loadings
- Large single crystals
- Minimum tool wear in comparison to other filler materials
- Physiologically safe

### **Typical Applications**

- Filler in thermal management applications
- Filler in thermal conductivity pastes and potting compounds
- Filler for silicone resins, thermoplastics and thermosets

### **Typical Values**

Colour: White
Boron Nitride: > 98.5 %
Total Oxygen: < 0.5 %</li>
Boron Oxide: < 0.1 %</li>
Carbon: < 0.1 %</li>
Specific Surface Area (BET): ~ 1 m²/g



## Packing Units

- ▶ 1 kg and 5 kg in plastic bags
- 25 kg in hard paper drums

# **Storage and Safety**

Keep dry. Minimum storage life 12 months in original packaging. For further information, please refer to safety data sheet.

The data quoted in this leaflet are typical for the material. They are intended as a guide only and should not be used in preparing detailed specifications. Actual product data may deviate from the figures given. We reserve the right to alter product data within the scope of technical progress and new developments. Since processing involves factors that are beyond our control, recommendations made in this leaflet should be checked by preliminary trials, especially for third party applications. These recommendations do not absolve the user from the obligation of investigating the possibility of infringement of third parties' rights and, if necessary, from clarifying the situation.